

BLF8G22LS-270V; BLF8G22LS-270GV

Power LDMOS transistor

Rev. 2 — 3 December 2012

Product data sheet

1. Product profile

1.1 General description

270 W LDMOS power transistor with improved video bandwidth for base station applications at frequencies from 2110 MHz to 2170 MHz.

Table 1. Typical performance

Typical RF performance at $T_{case} = 25\text{ °C}$ in a common source class-AB production test circuit, tested on straight lead device.

Test signal	f (MHz)	I_{Dq} (mA)	V_{DS} (V)	$P_{L(AV)}$ (W)	G_p (dB)	η_D (%)	ACPR _{5M} (dBc)
2-carrier W-CDMA	2110 to 2170	2400	28	80	17.3	29	-29 [1]

[1] 3GPP test model 1; 64 DPCH; PAR = 8.4 dB at 0.01 % probability on CCDF; 5 MHz carrier spacing.

1.2 Features and benefits

- Excellent ruggedness
- High efficiency
- Low R_{th} providing excellent thermal stability
- Designed for broadband operation
- Decoupling leads to enable improved video bandwidth (80 MHz typical)
- Lower output capacitance for improved performance in Doherty applications
- Designed for low memory effects providing excellent pre-distortability
- Internally matched for ease of use
- Integrated ESD protection
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)

1.3 Applications

- RF power amplifiers for base stations and multi carrier applications in the 2110 MHz to 2170 MHz frequency range



2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
BLF8G22LS-270V (SOT1244B)			
1	drain		<p>aaa-003619</p>
2	gate		
3	source		
4	video lead		
5	video lead		
6	n.c.		
7	n.c.		
BLF8G22LS-270GV (SOT1244C)			
1	drain		<p>aaa-003619</p>
2	gate		
3	source		
4	video lead		
5	video lead		
6	n.c.		
7	n.c.		

[1] Connected to flange.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BLF8G22LS-270V	-	earless flanged ceramic package; 6 leads	SOT1244B
BLF8G22LS-270GV	-	earless flanged ceramic package; 6 leads	SOT1244C

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage		-	65	V
V_{GS}	gate-source voltage		-0.5	+13	V
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		-	225	°C

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-c)}$	thermal resistance from junction to case	$T_{case} = 80\text{ °C}; P_L = 50\text{ W}$	0.26	K/W

6. Characteristics

Table 6. DC characteristics

$T_j = 25\text{ °C}$; per section unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{GS} = 0\text{ V}; I_D = 4.5\text{ mA}$	65	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$V_{DS} = 10\text{ V}; I_D = 450\text{ mA}$	1.5	1.8	2.3	V
I_{DSS}	drain leakage current	$V_{GS} = 0\text{ V}; V_{DS} = 28\text{ V}$	-	-	4.2	μA
I_{DSX}	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75\text{ V}; V_{DS} = 10\text{ V}$	-	80	-	A
I_{GSS}	gate leakage current	$V_{GS} = 11\text{ V}; V_{DS} = 0\text{ V}$	-	-	420	nA
g_{fs}	forward transconductance	$V_{DS} = 10\text{ V}; I_D = 450\text{ mA}$	-	3.8	-	S
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75\text{ V}; I_D = 15.75\text{ A}$	-	0.04	-	Ω

Table 7. RF characteristics

Test signal: 2-carrier W-CDMA; PAR = 8.4 dB at 0.01 % probability on the CCDF; 3GPP test model 1; 1-64 DPCH; $f_1 = 2112.5\text{ MHz}$; $f_2 = 2117.5\text{ MHz}$; $f_3 = 2162.5\text{ MHz}$; $f_4 = 2167.5\text{ MHz}$; RF performance at $V_{DS} = 28\text{ V}$; $I_{Dq} = 2400\text{ mA}$; $T_{case} = 25\text{ °C}$; unless otherwise specified; in a class-AB production test circuit, tested on straight lead device.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
G_p	power gain	$P_{L(AV)} = 80\text{ W}$	16.3	17.3	-	dB
RL_{in}	input return loss	$P_{L(AV)} = 80\text{ W}$	-	-17	-7	dB
η_D	drain efficiency	$P_{L(AV)} = 80\text{ W}$	26	29	-	%
$ACPR_{5M}$	adjacent channel power ratio (5 MHz)	$P_{L(AV)} = 80\text{ W}$	-	-29	-26.5	dBc

7. Test information

7.1 Ruggedness in class-AB operation

The BLF8G22LS-270V and BLF8G22LS-270GV are capable of withstanding a load mismatch corresponding to VSWR = 10 : 1 through all phases under the following conditions: $V_{DS} = 28\text{ V}$; $I_{Dq} = 2400\text{ mA}$; $P_L = 270\text{ W}$ (CW); $f = 2110\text{ MHz}$.

7.2 Impedance information

Table 8. Typical impedance information

$I_{Dq} = 2400\text{ mA}$; main transistor $V_{DS} = 28\text{ V}$.

Z_S and Z_L defined in [Figure 1](#).

f (MHz)	Z_S (Ω)	Z_L (Ω)
BLF8G22LS-270V		
2110	0.68 – j4.73	2.42 – j2.08
2140	0.80 – j4.94	2.67 – j2.24
2170	0.96 – j5.37	2.68 – j2.24
BLF8G22LS-270GV		
2110	1.23 – j6.94	2.39 – j4.22
2140	1.43 – j7.42	2.68 – j4.22
2170	1.44 – j7.50	2.90 – j4.30

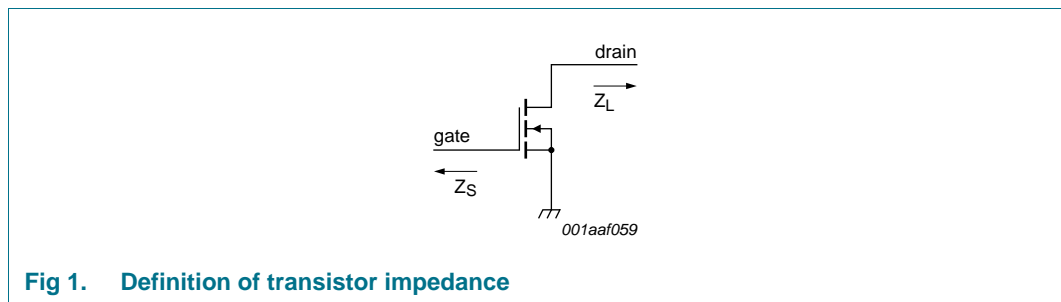


Fig 1. Definition of transistor impedance

7.3 Test circuit

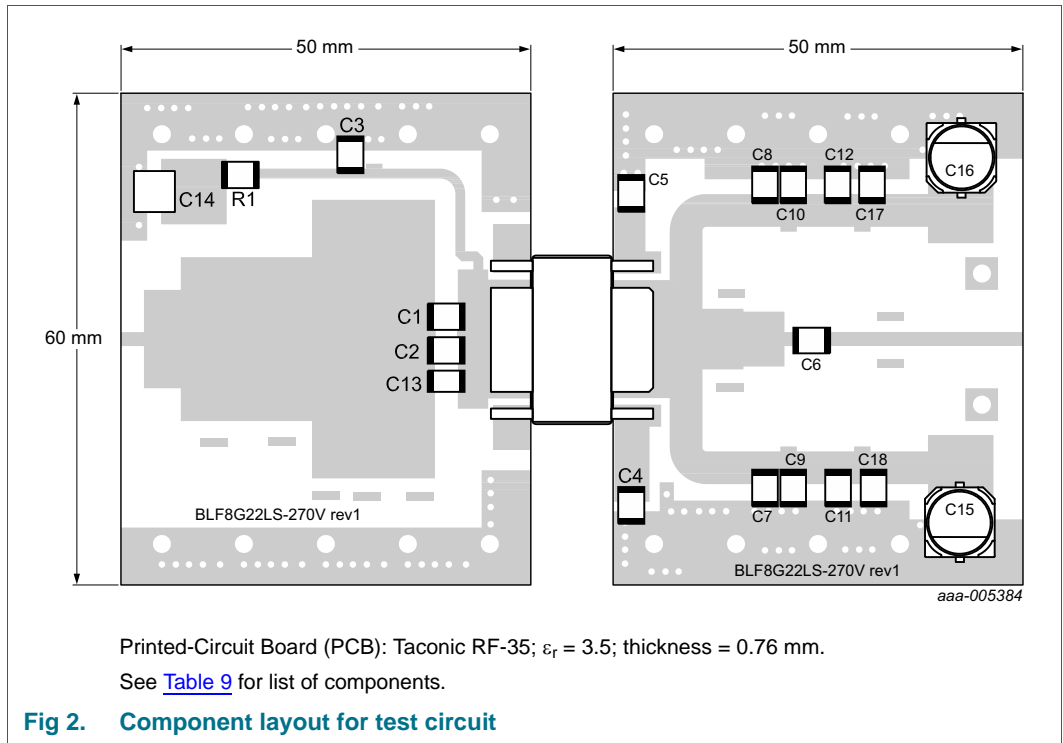


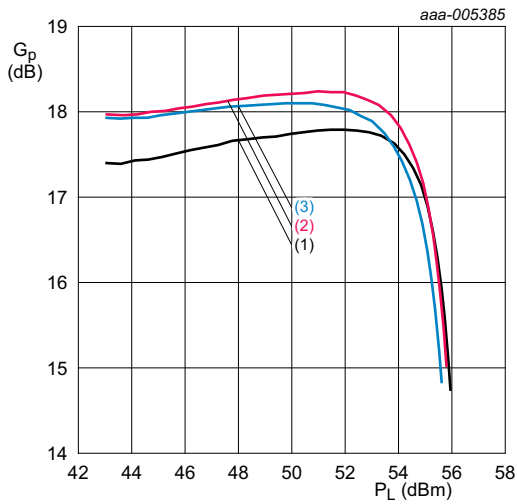
Table 9. List of components

For test circuit, see [Figure 2](#).

Component	Description	Value	Remarks
C1, C2	multilayer ceramic chip capacitor	0.7 pF	ATC100B
C3	multilayer ceramic chip capacitor	47 pF	ATC100B
C4, C5, C17, C18	multilayer ceramic chip capacitor	4.7 μ F, 50 V	Murata
C6	multilayer ceramic chip capacitor	33 pF	ATC100B
C7, C8	multilayer ceramic chip capacitor	12 pF	ATC100B
C9, C10, C11, C12	multilayer ceramic chip capacitor	100 pF	ATC100B
C13	multilayer ceramic chip capacitor	0.2 pF	ATC100B
C14	multilayer ceramic chip capacitor	10 μ F, 50 V	Murata; SMD 2220
C15, C16	electrolytic capacitor	470 μ F, 63 V	
R1	resistor	5.1 Ω	SMD 1206; tolerance = 1 %

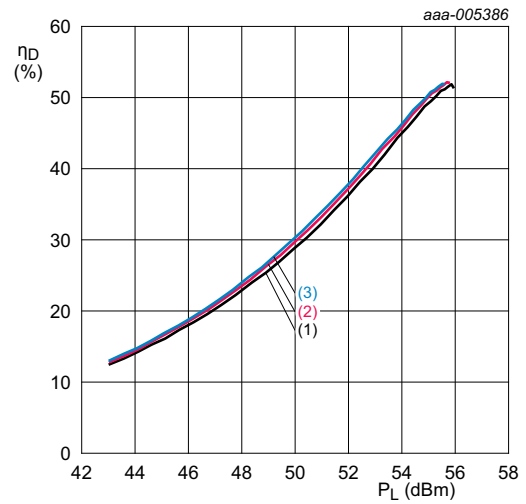
7.4 Graphs

7.4.1 Pulsed CW



$V_{DS} = 28\text{ V}; I_{DQ} = 2400\text{ mA}; t_p = 100\text{ }\mu\text{s}; \delta = 10\text{ }\%$.
 (1) $f = 2110\text{ MHz}$
 (2) $f = 2140\text{ MHz}$
 (3) $f = 2170\text{ MHz}$

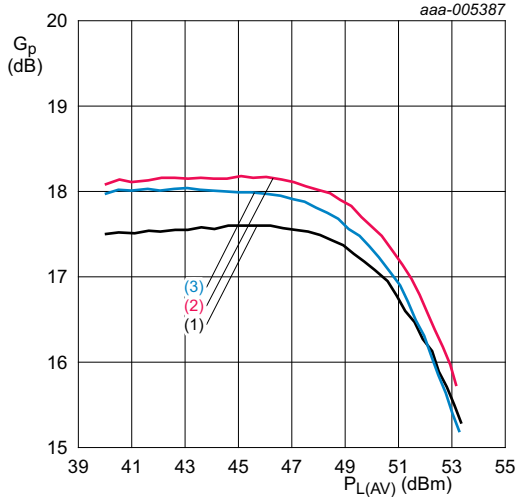
Fig 3. Power gain as a function of output power; typical values



$V_{DS} = 28\text{ V}; I_{DQ} = 2400\text{ mA}; t_p = 100\text{ }\mu\text{s}; \delta = 10\text{ }\%$.
 (1) $f = 2110\text{ MHz}$
 (2) $f = 2140\text{ MHz}$
 (3) $f = 2170\text{ MHz}$

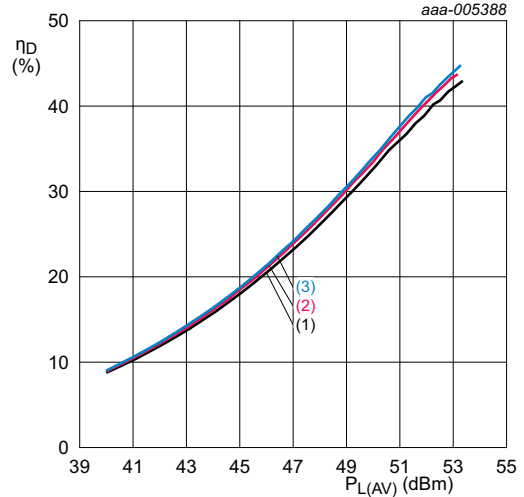
Fig 4. Drain efficiency as a function of output power; typical values

7.4.2 IS-95



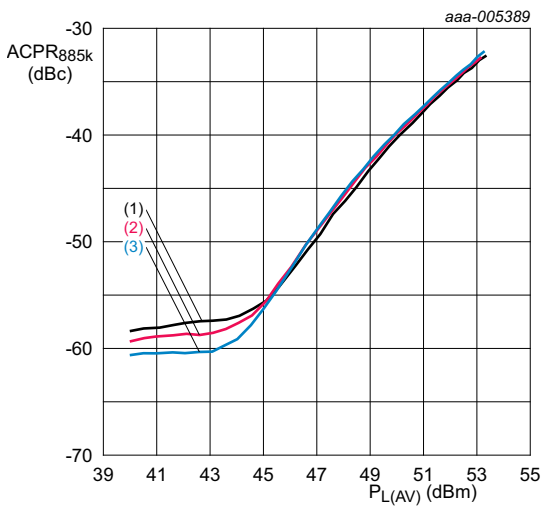
$V_{DS} = 28\text{ V}; I_{Dq} = 2400\text{ mA}.$
 (1) $f = 2110\text{ MHz}$
 (2) $f = 2140\text{ MHz}$
 (3) $f = 2170\text{ MHz}$

Fig 5. Power gain as a function of average output power; typical values



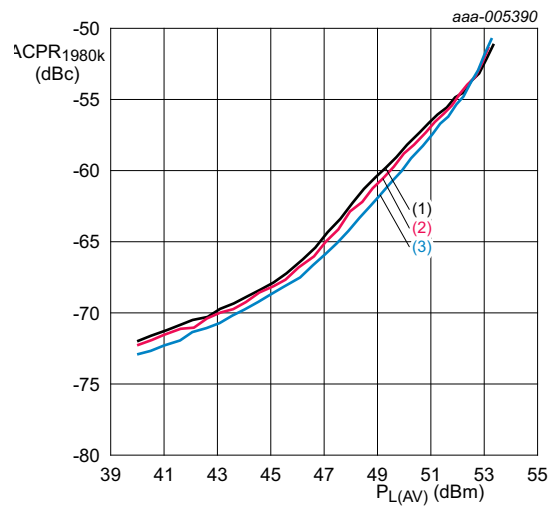
$V_{DS} = 28\text{ V}; I_{Dq} = 2400\text{ mA}.$
 (1) $f = 2110\text{ MHz}$
 (2) $f = 2140\text{ MHz}$
 (3) $f = 2170\text{ MHz}$

Fig 6. Drain efficiency as a function of average output power; typical values



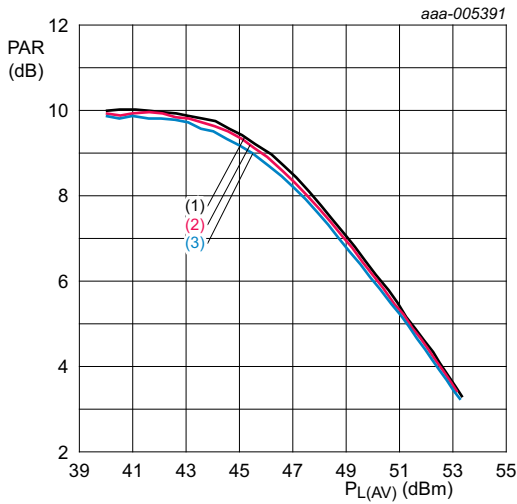
$V_{DS} = 28\text{ V}; I_{Dq} = 2400\text{ mA}.$
 (1) $f = 2110\text{ MHz}$
 (2) $f = 2140\text{ MHz}$
 (3) $f = 2170\text{ MHz}$

Fig 7. Adjacent channel power ratio (885 kHz) as a function of average output power; typical values



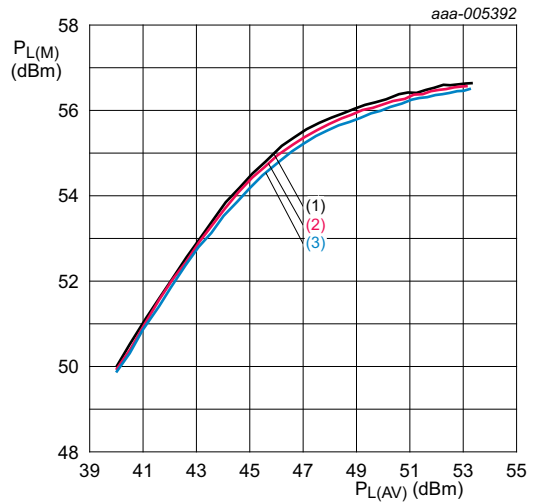
$V_{DS} = 28\text{ V}; I_{Dq} = 2400\text{ mA}.$
 (1) $f = 2110\text{ MHz}$
 (2) $f = 2140\text{ MHz}$
 (3) $f = 2170\text{ MHz}$

Fig 8. Adjacent channel power ratio (1980 kHz) as a function of average output power; typical values



$V_{DS} = 28\text{ V}; I_{Dq} = 2400\text{ mA}.$
 (1) $f = 2110\text{ MHz}$
 (2) $f = 2140\text{ MHz}$
 (3) $f = 2170\text{ MHz}$

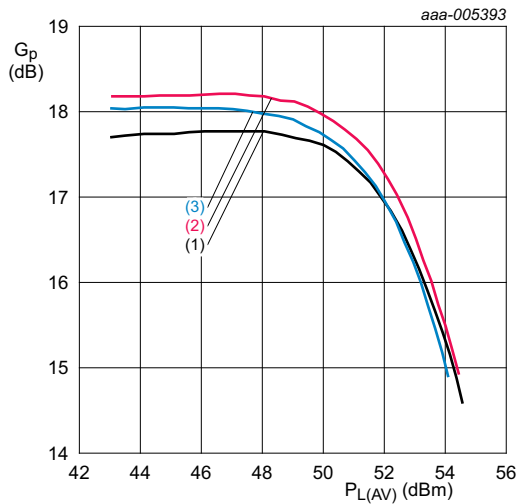
Fig 9. Peak-to-average power ratio as a function of average output power; typical values



$V_{DS} = 28\text{ V}; I_{Dq} = 2400\text{ mA}.$
 (1) $f = 2110\text{ MHz}$
 (2) $f = 2140\text{ MHz}$
 (3) $f = 2170\text{ MHz}$

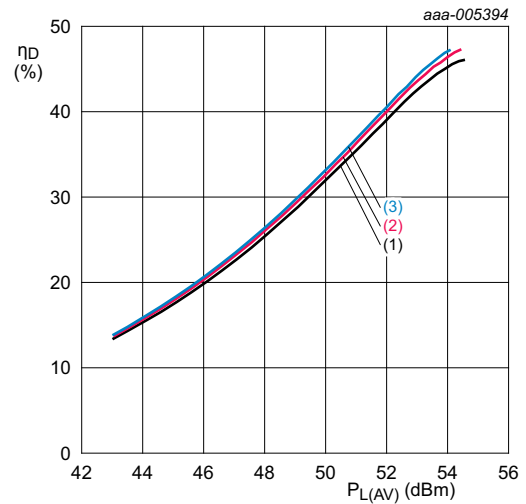
Fig 10. Peak output power ratio as a function of average output power; typical values

7.4.3 1-carrier W-CDMA



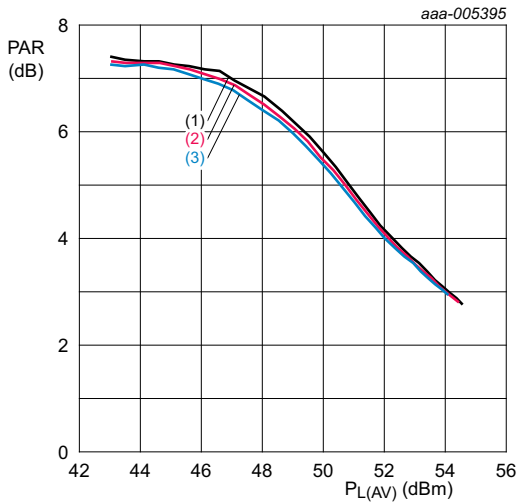
$V_{DS} = 28\text{ V}; I_{Dq} = 2400\text{ mA}.$
 (1) $f = 2112.5\text{ MHz}$
 (2) $f = 2140\text{ MHz}$
 (3) $f = 2167.5\text{ MHz}$

Fig 11. Power gain as a function of average output power; typical values



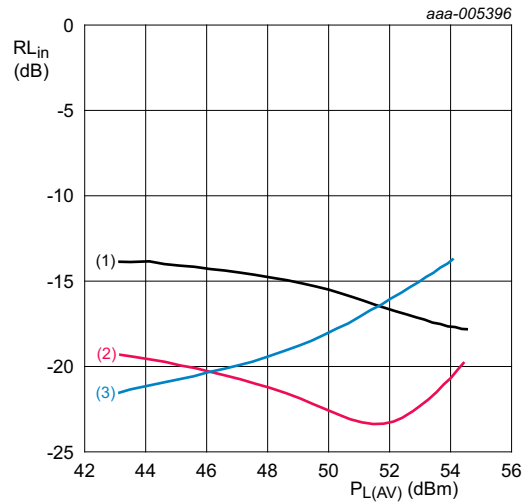
$V_{DS} = 28\text{ V}; I_{Dq} = 2400\text{ mA}.$
 (1) $f = 2112.5\text{ MHz}$
 (2) $f = 2140\text{ MHz}$
 (3) $f = 2167.5\text{ MHz}$

Fig 12. Drain efficiency as a function of average output power; typical values



$V_{DS} = 28\text{ V}$; $I_{Dq} = 2400\text{ mA}$.
 (1) $f = 2112.5\text{ MHz}$
 (2) $f = 2140\text{ MHz}$
 (3) $f = 2167.5\text{ MHz}$

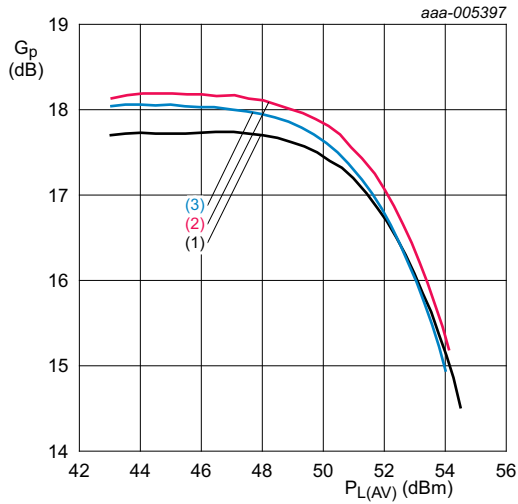
Fig 13. Peak-to-average power ratio as a function of average output power; typical values



$V_{DS} = 28\text{ V}$; $I_{Dq} = 2400\text{ mA}$.
 (1) $f = 2112.5\text{ MHz}$
 (2) $f = 2140\text{ MHz}$
 (3) $f = 2167.5\text{ MHz}$

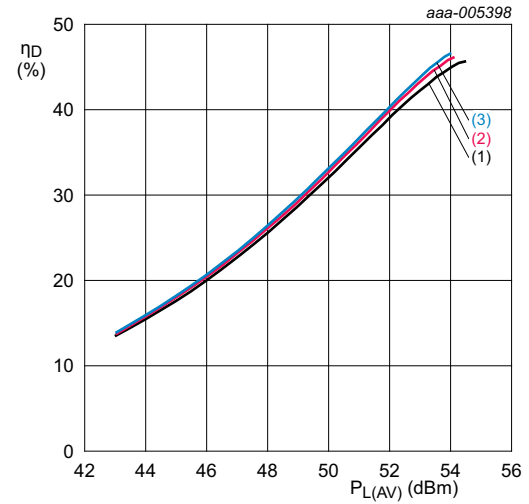
Fig 14. Input return loss as a function of average output power; typical values

7.4.4 2-carrier W-CDMA



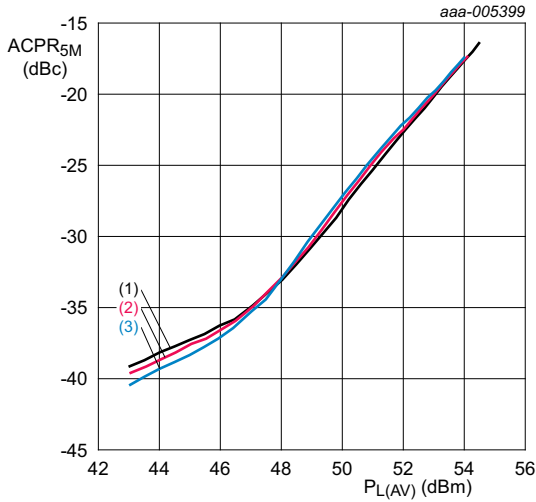
$V_{DS} = 28\text{ V}$; $I_{Dq} = 2400\text{ mA}$; 5 MHz carrier spacing.
 (1) $f = 2115\text{ MHz}$
 (2) $f = 2140\text{ MHz}$
 (3) $f = 2165\text{ MHz}$

Fig 15. Power gain as a function of average output power; typical values



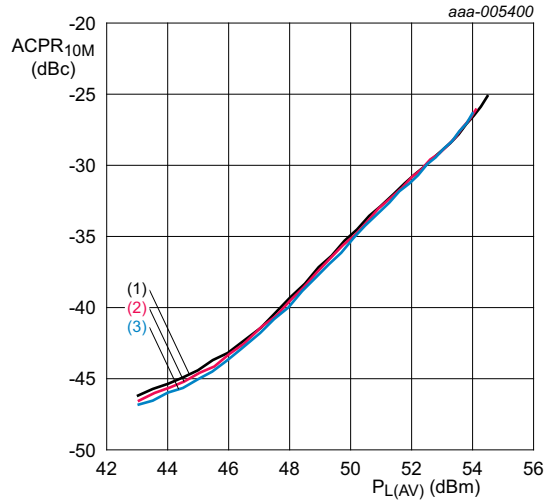
$V_{DS} = 28\text{ V}$; $I_{Dq} = 2400\text{ mA}$; 5 MHz carrier spacing.
 (1) $f = 2115\text{ MHz}$
 (2) $f = 2140\text{ MHz}$
 (3) $f = 2165\text{ MHz}$

Fig 16. Drain efficiency as a function of average output power; typical values



$V_{DS} = 28\text{ V}$; $I_{Dq} = 2400\text{ mA}$; 5 MHz carrier spacing.
 (1) $f = 2115\text{ MHz}$
 (2) $f = 2140\text{ MHz}$
 (3) $f = 2165\text{ MHz}$

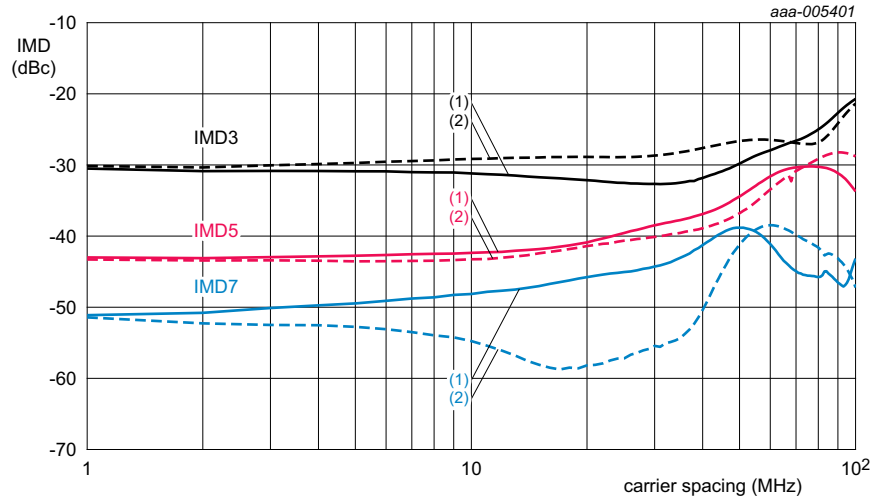
Fig 17. Adjacent channel power ratio (5 MHz) as a function of average output power; typical values



$V_{DS} = 28\text{ V}$; $I_{Dq} = 2400\text{ mA}$; 5 MHz carrier spacing.
 (1) $f = 2115\text{ MHz}$
 (2) $f = 2140\text{ MHz}$
 (3) $f = 2165\text{ MHz}$

Fig 18. Adjacent channel power ratio (10 MHz) as a function of average output power; typical values

7.4.5 2-Tone VBW



$V_{DS} = 28\text{ V}$; $I_{Dq} = 2400\text{ mA}$; $f = 2140\text{ MHz}$.
 (1) IMD low
 (2) IMD high

Fig 19. VBW capability in class-AB test circuit

8. Package outline

Earless flanged ceramic package; 6 leads

SOT1244B

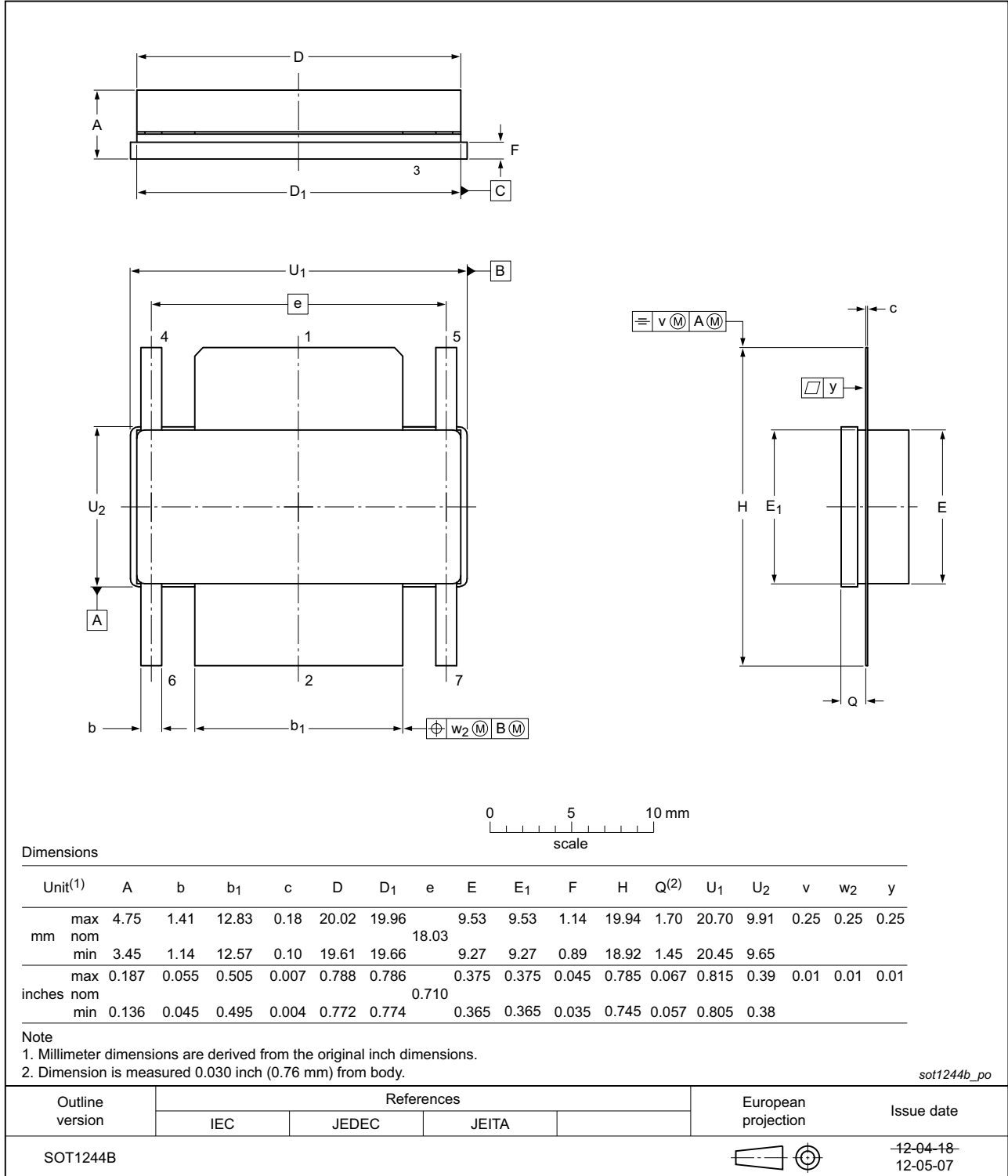


Fig 20. Package outline SOT1244B

Earless flanged ceramic package; 6 leads

SOT1244C

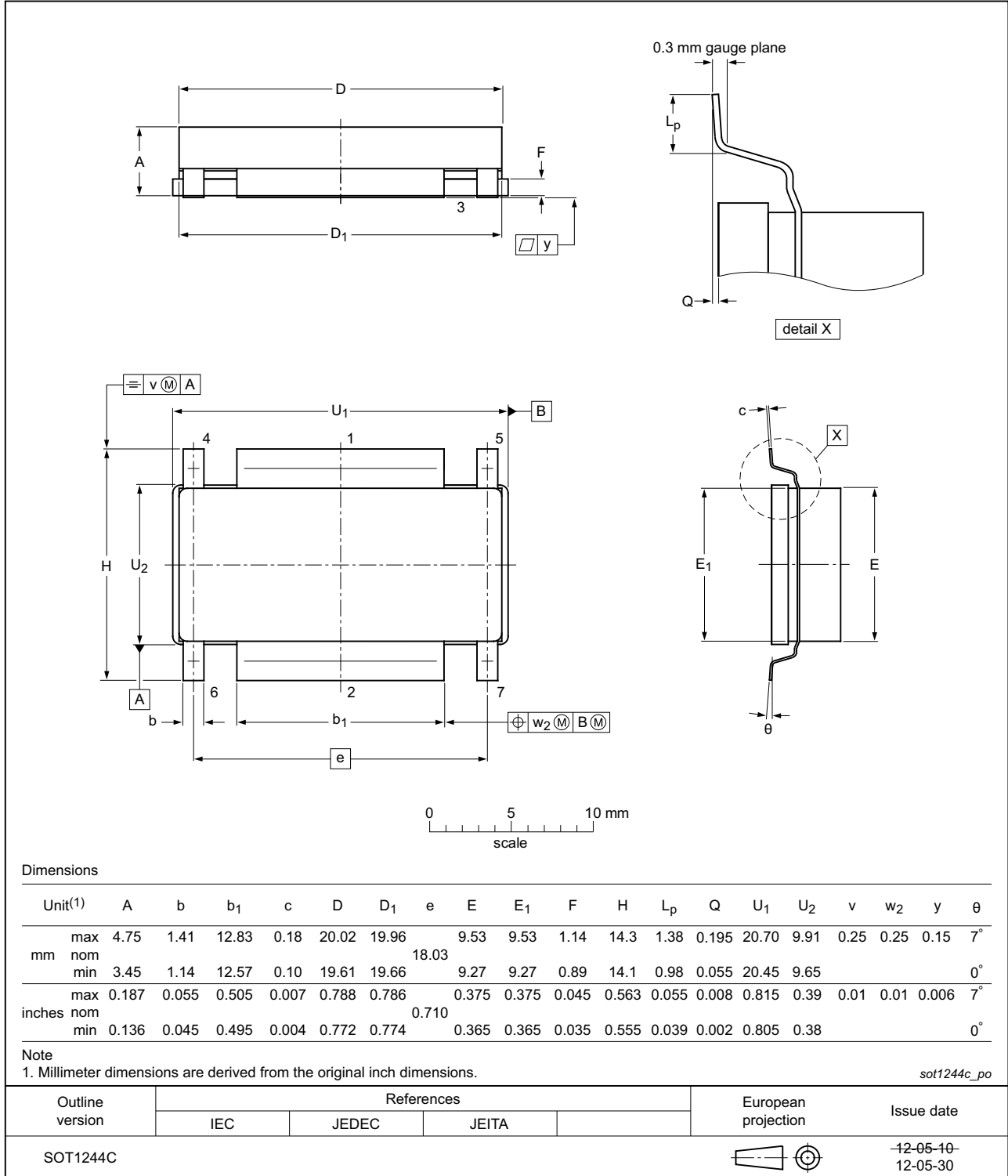


Fig 21. Package outline SOT1244C

9. Handling information

CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or equivalent standards.

10. Abbreviations

Table 10. Abbreviations

Acronym	Description
3GPP	3rd Generation Partnership Project
CCDF	Complementary Cumulative Distribution Function
CW	Continuous Wave
DPCH	Dedicated Physical Channel
ESD	ElectroStatic Discharge
IS-95	Interim Standard 95
LDMOS	Laterally Diffused Metal Oxide Semiconductor
PAR	Peak-to-Average Ratio
SMD	Surface Mounted Device
VBW	Video BandWidth
VSWR	Voltage Standing Wave Ratio
W-CDMA	Wideband Code Division Multiple Access

11. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BLF8G22LS-270V_8G22LS-270GV v.2	20121203	Product data sheet	-	BLF8G22LS-270V_8G22LS-270GV v.1
Modifications:				
				<ul style="list-style-type: none"> • Section 1.1 on page 1: improved video bandwidth has been mentioned. • Table 1 on page 1: several values have been changed. • Section 1.2 on page 1: section has been updated. • Table 4 on page 2: row containing I_D has been removed. • Table 5 on page 3: some values have been added. • Table 7 on page 3: table has been moved to Section 6 on page 3. • Table 7 on page 3: several values have been changed. • Section 7.1 on page 3: section has been added. • Section 7.2 on page 4: section has been added. • Section 7.3 on page 5: section has been added. • Section 7.4 on page 6: section has been added.
BLF8G22LS-270V_8G22LS-270GV v.1	20120613	Objective data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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For sales office addresses, please send an email to: salesaddresses@nxp.com

14. Contents

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